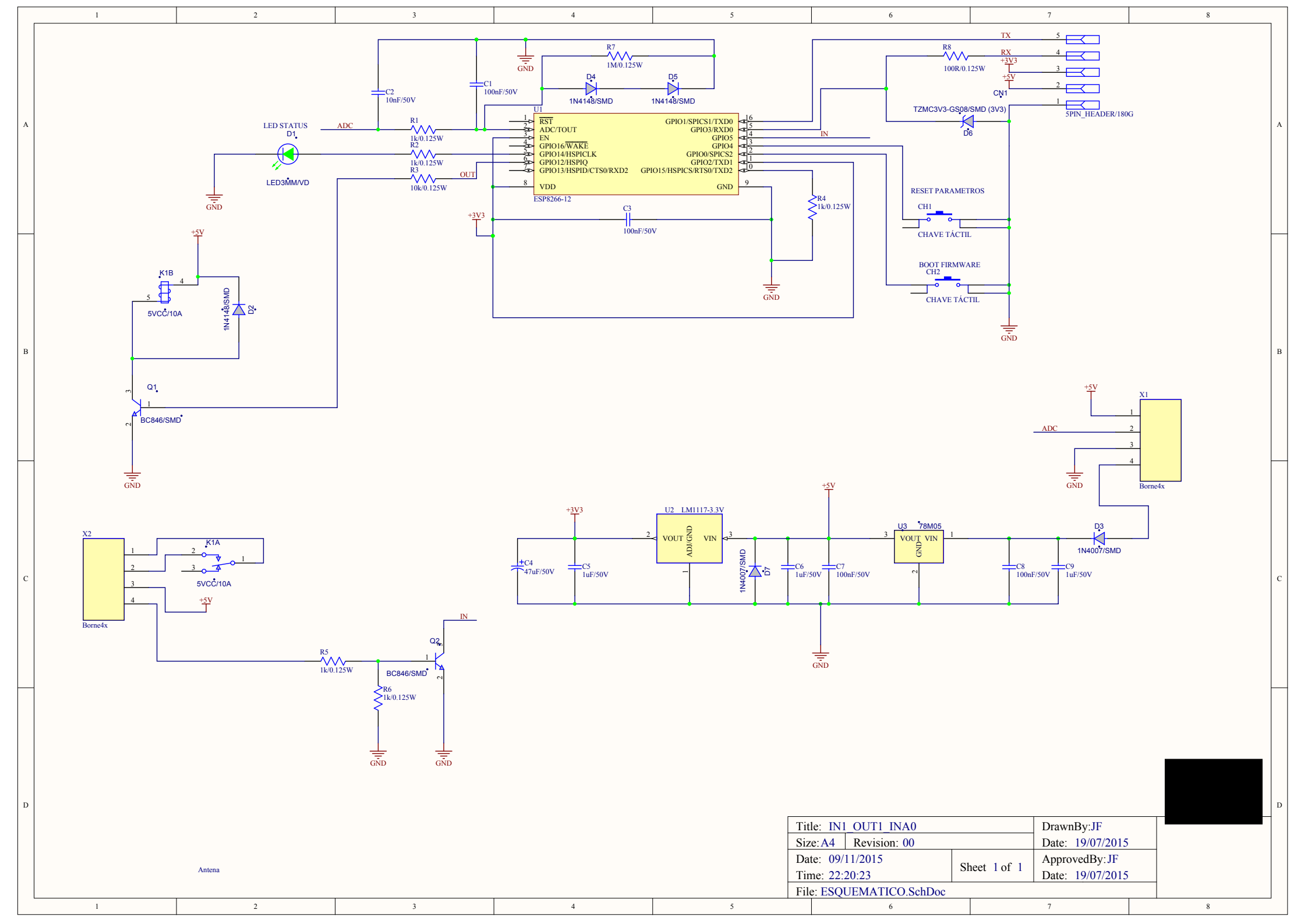


Title: IN1_OUT1_INA0		DrawnBy: JF
Size: A4 Revision: 00		Date: 19/07/2015
Date: 09/11/2015 Time: 22:20:23	Sheet 1 of 1	ApprovedBy: JF Date: 19/07/2015
File: ESQUEMATICO.SchDoc		

RECOMMENDED LAYUP

LAYER STACK CONFIGURATION

1 LAYER BUILD

TOP LAYER TL — COPPER CLAD — 35 Micron H.T.E 1.4mil

BOTTOM LAYER BL — COPPER CLAD — 35 Micron H.T.E 1.4mil

BOARD THICKNESS: 1.6mm (61.2mil)

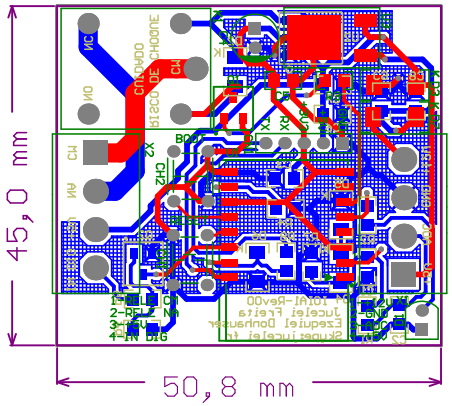
MATERIAL: FENOLITE

LAYER

BOTTOM

LAYER USAGE

- TOP OVERLAY
- TOP LAYER
- BOTTOM LAYER
- BOTTOM OVERLAY
- BOARD OUTLINE
- MULTILAYER
- TECHNICAL DATA
- MANUFACTURE DATA
- IDENTIFICATION DATA
- DIMENSIONS
- ROUTING KEEPOUT LAYER



PCB DESIGNER: .ProjetcDesigner		
DATE: 09/11/2015	PART NO.:	REV: 00
FILE NAME: IN1_OUT1_INA0	DWG NO:	SCALE: 1:1

Descrição	Designator	Quantity
Capacitor SMD 0805 - 100nF/50V	C1, C3, C7, C8	4
Capacitor SMD 0805 - 10nF/50V	C2	1
Capacitor Eletrolítico 100mils - 47uF/50V	C4	1
Capacitor SMD 0805 - 1uF/50V	C5, C6, C9	3
Chave táctil com haste 180º e de 4mm (6mm x 6mm x 9mm)	CH1, CH2	2
Conector Metaltex 180º BPSC40 (5x)	CN1	1
Led verde difuso de 3mm	D1	1
Diodo de sinal 1N4148 SMD	D2, D4, D5	3
Diodo retificador 1A/1000V 1N4007 (SM4007A) SMD	D3, D7	2
Diodo Zener 3V3 SMD	D6	1
Rele AY1RC-5V - 5VCC/10A	K1	1
Transistor BC846/SMD	Q1, Q2	2
Resistor SMD 0805 - 1k/0.125W	R1, R2, R4, R5, R6	5
Resistor SMD 0805 - 10k/0.125W	R3	1
Resistor SMD 0805 - 1M/0.125W	R7	1
Resistor SMD 0805 - 100R/0.125W	R8	1
ESP8266-12 Wi-Fi Module	U1	1
Regulador de tensão linear 1117-3.3V	U2	1
Circuito Integrado 78M05/DPAK-3	U3	1
Borne de 4 vias para pci com fixação a parafuso 5.08mm	X1, X2	2